

98426-YXX-XX-XXXLF

PLATING

- G : 0.76 GXT
2µm MIN MATTE TIN ON TAIL
- S : 0.38 GXT
2µm MIN MATTE TIN ON TAIL
- F : GOLD FLASH /2µm MIN TIN ON TAIL
- T : 2µm MIN FULL TIN
1.27µm NICKEL MIN UNDERPLATING

- LEAD FREE AND RoHS
COMPATIBLE, NOTE 6
- BODY HEIGHT : XXX
 - MIN= 104 (10.4MM)
 - MAX= 290 (29.0MM)

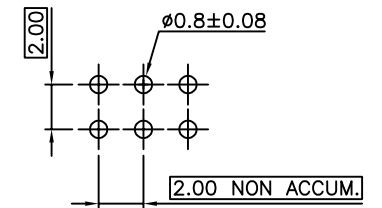
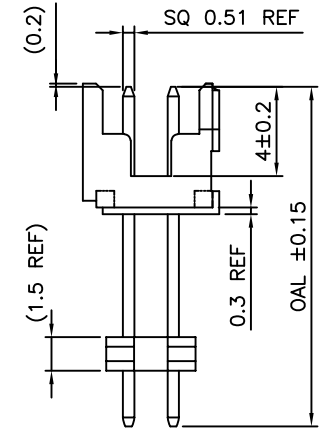
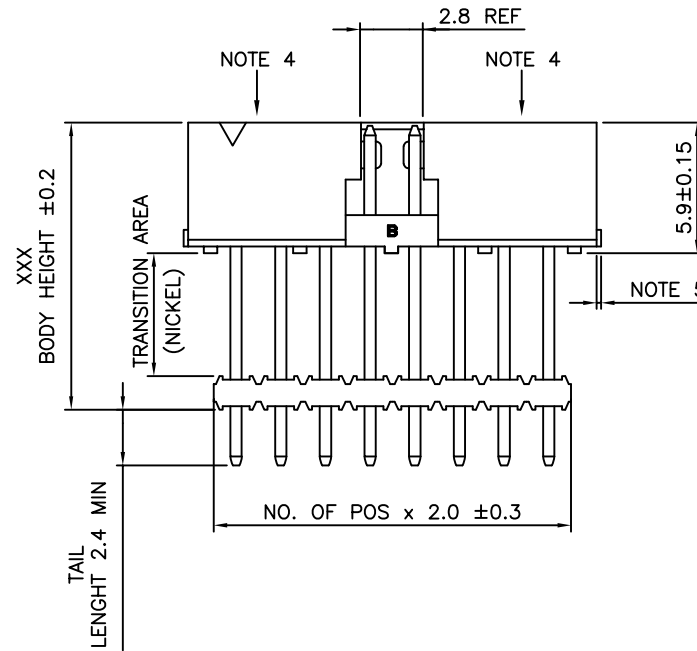
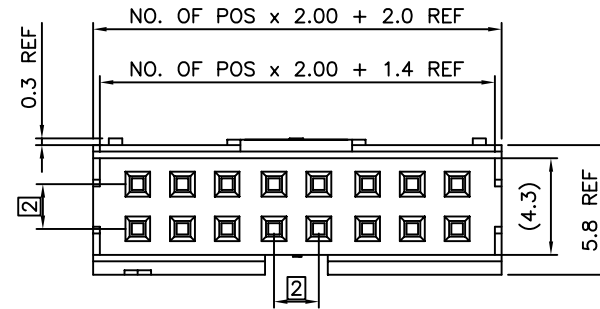
PACKAGING, NOTE 3

NO. OF POS PER ROW, 03 TO 25

NOTES:

- MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC
UL 94V-0, COLOR CREAM (SHROUD)
AND BLACK(UNSHROUDED)
- MATERIAL TERMINAL: COPPER ALLOY
- PACKAGING
 - = STANDARD PACKAGING IN BLIBOX
 - S = CUSTOM PACKAGING IN TUBE
ONLY FOR PIN STYLE 17
- SHROUDED RETENTION FORCE 3N MIN PER POSITION
- 0.3 MAX PROTRUSION FOR -03 TO 11
- RoHS COMPATIBLE PRODUCT SPECIFICATIONS
 - PLATING:
 - "LF" MEANS THE PRODUCT IS LEAD-FREE,
2µm MINIMUM MATTE TIN OVER 1.27µm
MINIMUM NICKEL UNDERPLATE.
 - MANUFACTURING PROCESS COMPATIBILITY
 - THE HOUSING WILL WITHSTAND EXPOSURE TO
260°C ±5°C SOLDER BATH TEMPERATURE FOR
5 SECONDS IN A WAVE SOLDER APPLICATION
WITH A 1.6mm MIN THICK CIRCUIT BOARD.
 - LABELING:
 - MEETS PACKAGING SPECS AS PER GS-14-920
 - LEGAL STATEMENT: SEE GS-47-0004
- THIS PRODUCT IS NOT INTENDED TO BE USED THROUGH REFLOW PROCESS

PIN STYLE	OAL
01	12.8
02	13.5
03	14.1
04	15.6
05	16.3
06	17.1
07	18.3
08	19.1
09	20.3
10	21.1
11	22.3
12	23.3
13	26.0
14	28.0
15	30.0
16	32.0
17	11.0
18	33.0
19	38.00



RECOMMENDED HOLE PATTERN

mat'l. code				surface	tolerance	projection	product family		
				ISO 1302	ISO 406	ISO 101	MINITEK		
ltr	ecn no	dr	date	tolerances unless otherwise specified			title		
				angles	linear	mm	SHR STACKING HEADER MINITEK		
C	B-18972	LMU	14.10.01		X.X ±0.3		scale 1:1		
D	B-19190	LMU	14.10.24	dr	X.XX ±0.13		dwg no		
E	B-20291	BVE	15.02.19	engr	X.XXX ±0.05		sheet 1 of 1		
F	F-27987	LMU	17.09.18	chr			size		
G	F-47166	DDE	23.02.01	app			A3		
sheet				revision			type		
index				sheet			CUSTOMER Drawing		